HOSTAFORM® M10AE

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POM copolymer
Stiff-flowing type with high melt strength; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation.
Monomers and additives are listed in EU-Regulation (EU) 10/2011 FDA compliant according to 21 CFR 177.2470
Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm.
Ranges of applications: For extrusion blow molding, and for injection molding thick-walled, void-free molded parts.

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	0.9	cm^3/10min	ISO 1133
Temperature	374	°F	
Load	4.76	lb	

Typical mechanical properties

Tensile modulus	406000	psi	ISO 527-1/-2
Tensile stress at yield, 50mm/min	9400	psi	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	25	%	ISO 527-1/-2
Tensile creep modulus, 1h	348000	psi	ISO 899-1
Tensile creep modulus, 1000h	174000	psi	ISO 899-1
Charpy impact strength, 23°C	105[P]	ftlb/in^2	ISO 179/1eU
Charpy impact strength, -30°C	95.1	ftlb/in^2	ISO 179/1eU
Charpy notched impact strength, 23°C	4.76	ftlb/in^2	ISO 179/1eA
Charpy notched impact strength, -30°C	3.81	ftlb/in^2	ISO 179/1eA

[P]: Partial Break

Thermal properties

Melting temperature, 10°C/min	333	°F	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	207	°F	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	0.72	E-4/°F	ISO 11359-1/-2

Electrical properties

Relative permittivity, 100Hz	4		IEC 62631-2-1
Relative permittivity, 1MHz	4		IEC 62631-2-1
Dissipation factor, 100Hz	20	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50	E-4	IEC 62631-2-1
Volume resistivity	1E12	Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	Ohm	IEC 62631-3-2
Electric strength	711	kV/in	IEC 60243-1
Comparative tracking index	600		IEC 60112

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Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	0.0509	lb/in³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	392	°F
Min. melt temperature	374	°F
Max. melt temperature	410	°F
Max. screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	212	°F
Min. mold temperature	176	°F
Max. mold temperature	248	°F
Hold pressure range	8700 - 17400	psi
Hold Pressure Time (h is the max. wall thickness of the part in mm)	2h²-3	s
Back pressure	580	psi
Ejection temperature	282	°F

Characteristics

Processing	Injection Molding, Film Extrusion, Extrusion, Sheet Extrusion, Other Extrusion, Blow Molding, Extrusion Blow Molding
Additives	Release agent
Special characteristics	High viscosity

Additional information

Film extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

HOSTAFORM® M10AE

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Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C
Annealing time 10 min/mm thickness

Other extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C
Annealing time 10 min/mm thickness

Profile extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of

the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C
Annealing time 10 min/mm thickness

Sheet extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

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Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C
Annealing time 10 min/mm thickness

Blow molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with plasticating screws (20 to 25 D) will fit.

Melt temperature 180-190 °C
Mould-surface temperature 60-100 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granul

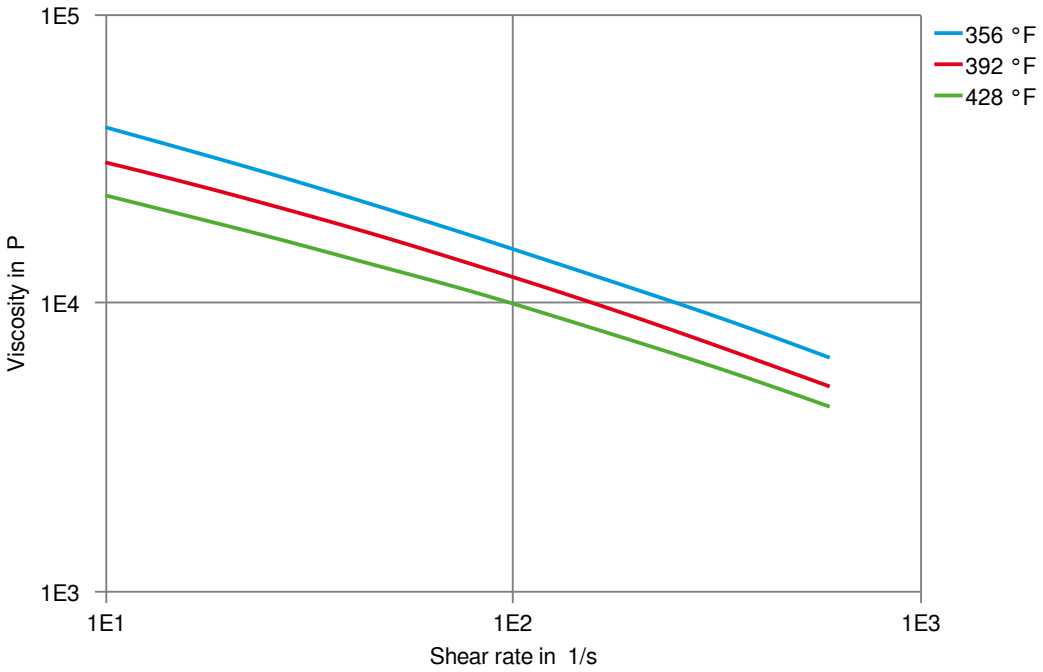
Storage

The product can then be stored in standard conditions until processed.

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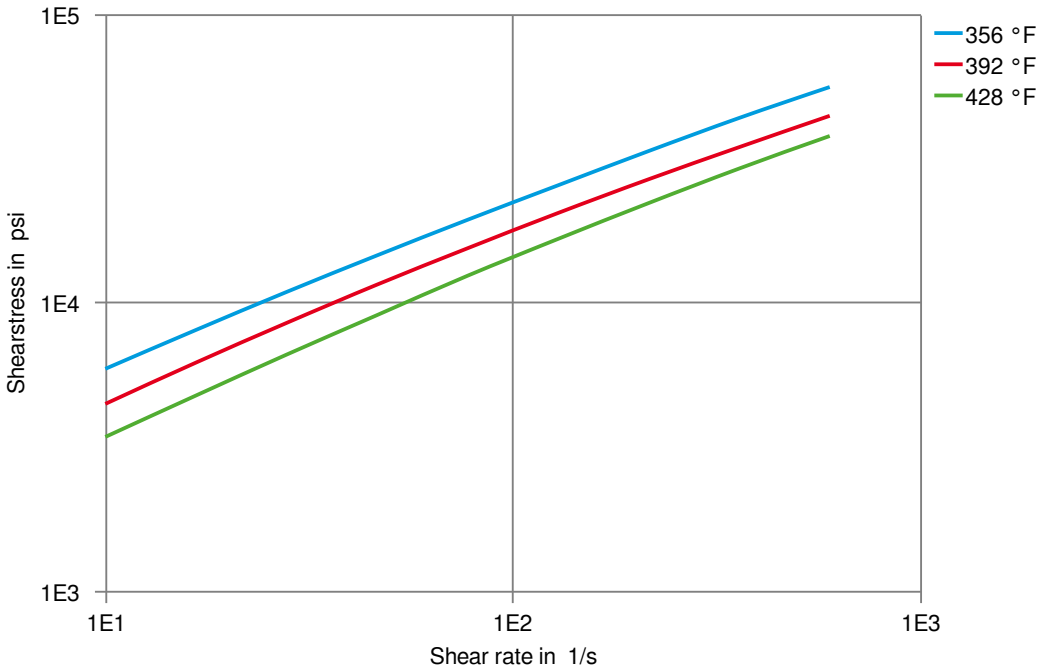
Viscosity-shear rate



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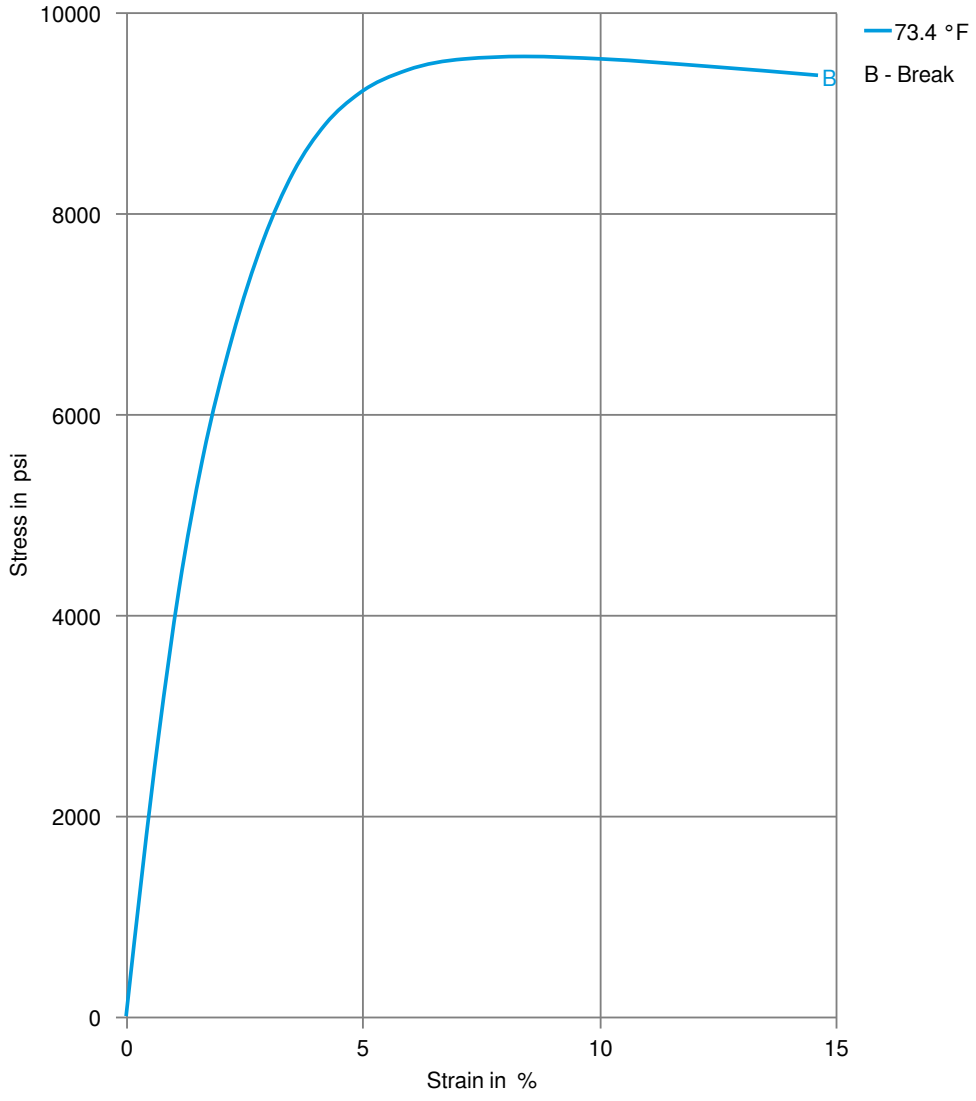
Shearstress-shear rate



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Stress-strain

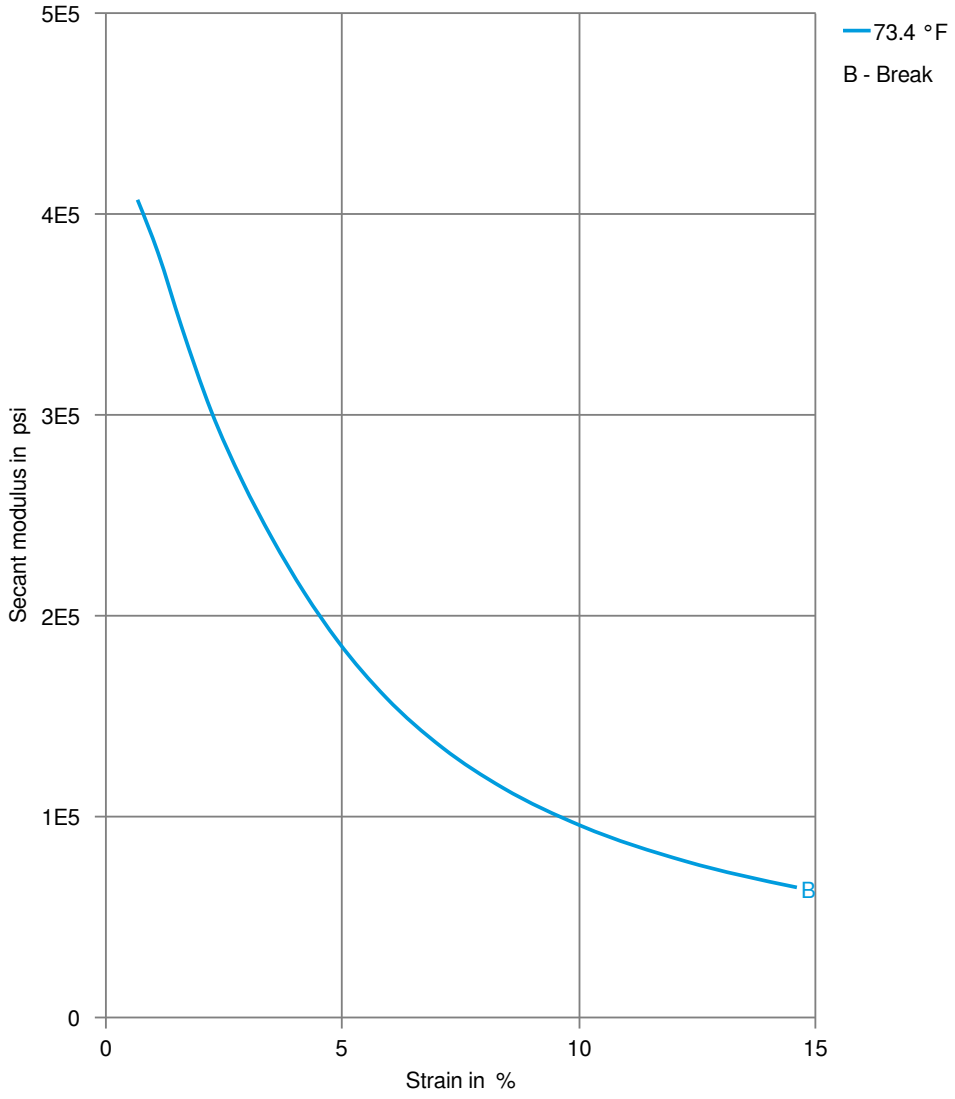


Revised: 2025-07-23 Source: Celanese Materials Database

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Secant modulus-strain



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